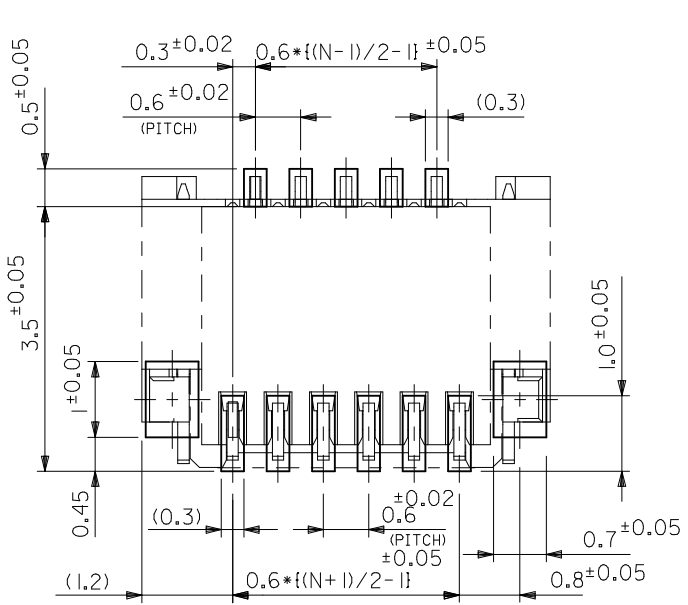


10.2	9.0	9.6	12.0	500797-3394	500797-3350	33
9.6	8.4	9.0	11.4	500797-3194	500797-3150	31
8.4	7.2	7.8	10.2	500797-2794	500797-2750	27
7.2	6.0	6.6	9.0	500797-2394	500797-2350	23
3.6	2.4	3.0	5.4	500797-1194	500797-1150	11
D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	CKT.
				ORDER No. オーダー番号	500797-**50	MODEL No.

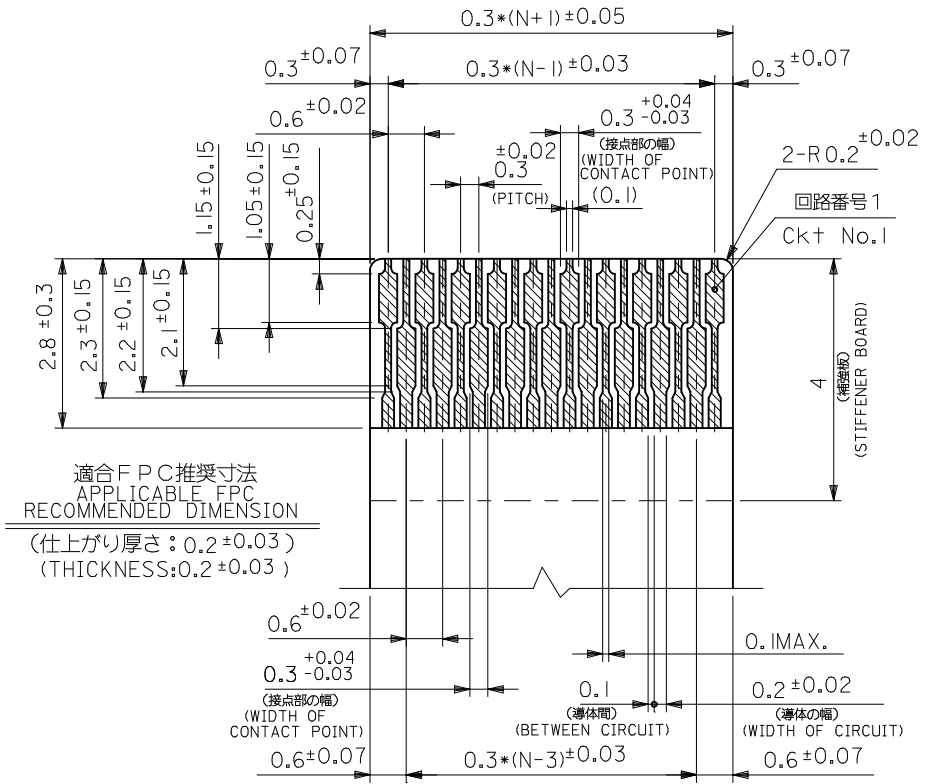
REVISED EC NO: J2016-1099 DRWN:MTAKAHASHI 2016/04/19 CHKD:KTAHAKASHI 2016/04/26 APPR:KUSUHARA01 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY MTANAKA	DATE 2006/03/07	molex DOCUMENT NO. SD-500797-005 SHEET NO. 1 OF 2	
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE 2006/03/07		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		SEE TABLE	
30 OVER		±0.25	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
ANGULAR		±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				



参考基板レイアウト図
(マウント面)
(MOUNTING SIDE)

注記 NOTES

1. 使用材料 MATERIAL
 ハウジング : 液晶ポリマー ガラス充填 UL94V-0
 HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0
 アクチュエータ : 46 ナイロン ガラス充填 UL94V-0
 ACTUATOR : 46 NYLON (GLASS FILLED) UL94V-0
 ターミナル : 銅合金 (t=0.15), ニッケル下地金メッキ
 TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.
 金具 : リン青銅 (t=0.15), ニッケル下地スズメッキ
 FITTING NAIL : PHOSPHOR-BRONZE, TIN OVER NICKEL PLATING.
 △ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 □ に対し、
 上方向 0.1MAXIMUM 下方向 0.15MAXIMUM とする。
 又、相互のバラツキ量は 0.1MAXIMUM とする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM □
 UPPER DIRECTION : 0.1 MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.
 OFFSET BETWEEN SOLDER TAILS AND FITTING NAILS : 0.1 MAXIMUM.



適合FPC推奨寸法
 APPLICABLE FPC
 RECOMMENDED DIMENSION
 (仕上がり厚さ: 0.2±0.03)
 (THICKNESS: 0.2±0.03)

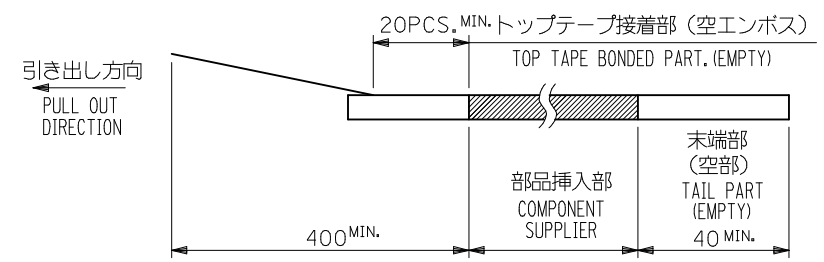
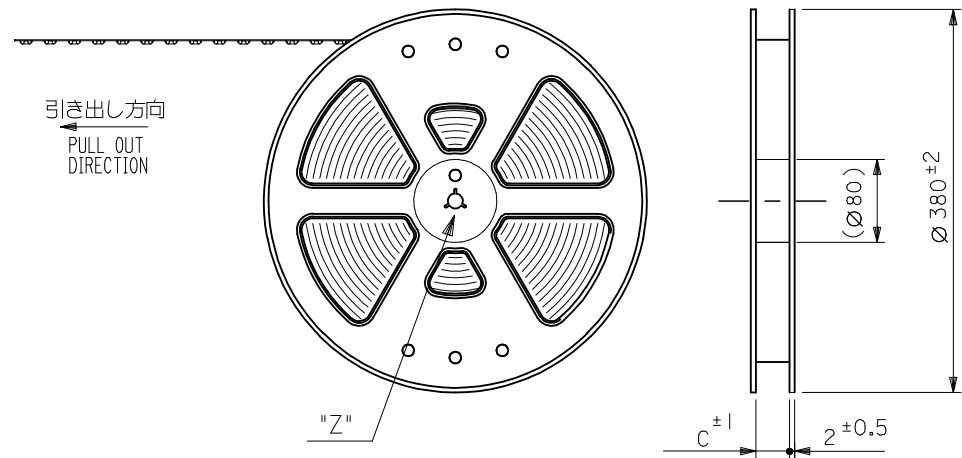
FPCについて:
 打抜き方向は導体側から補強板側を推奨いたします。
 導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを
 推奨致します。
 補強フィルム材質はポリイミドを推奨します。
 接着剤は熱硬化接着剤を推奨します。

ABOUT FPC
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
 RECOMMENDED CONDUCTOR SPEC :
 THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER
 RECOMMENDED MATERIAL :
 STIFFENER FILM : POLYIMIDE
 BONDING AGENT : THERMOSETTING BONDING AGENT

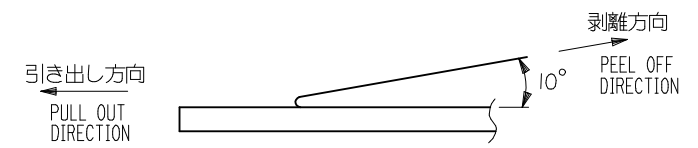
REVISED EC NO: J2016-1099 DRWN:MTAKAHASHI 2016/04/19 CHKD:KATAHASHI 2016/04/26 APPR:TKUSUHARA01 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 500797-**50
	0.25 UNDER	UNDER	±0.03	DRAWN BY YMAEDA	DATE 2006/03/06	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY MTANAKA	DATE 2006/03/06		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE 2006/03/06		
1.0 OVER	10 UNDER	±0.2	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
10 OVER	30 UNDER	±0.25	SIZE A3				
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
J	REVISION						

NOTES

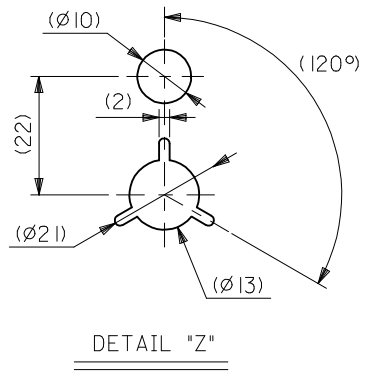
- 製品詳細寸法については図面 SD-500797-005 を参照下さい。
RE DETAILED DIMENSION, SEE SD-500797-005
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：0.1N ~ 1.3N(10.2gf ~ 132.6gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG,)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.

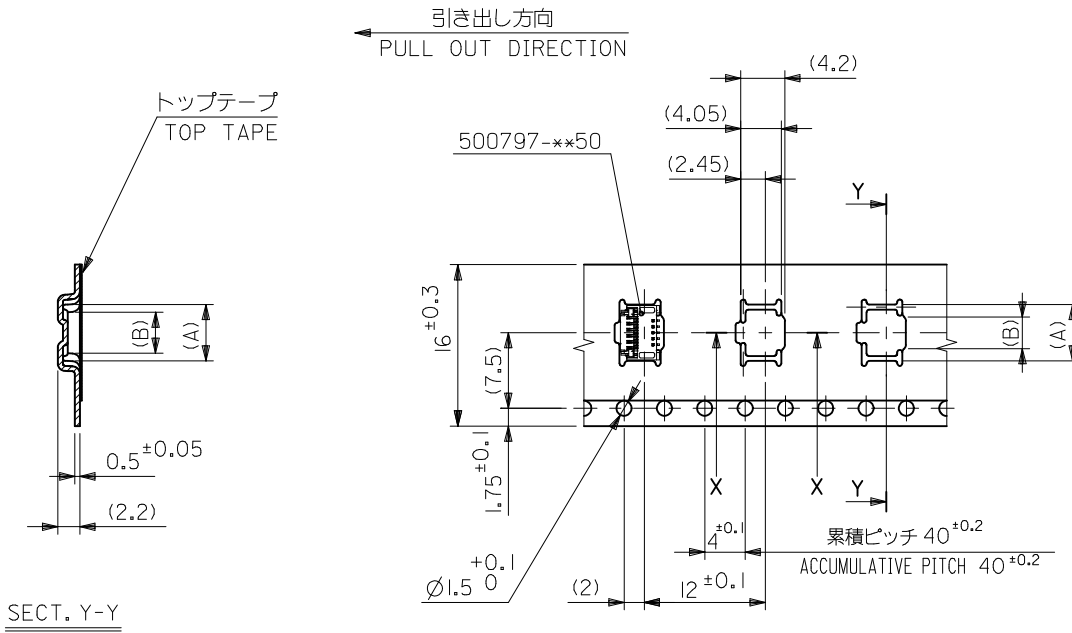


- 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)
トップテープ(TOP TAPE)：PET, PE, PEF
リール(REEL)：ポリスチレン(PS) <リサイクル材含む>
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>
- C寸法は SHEET 2 ~ 4 を参照下さい。
SEE SHEET 2 ~ 4 (DIMENSION C).
- 欠品無きこと。
THERE SHALL BE NO MISSING PRODUCTS.



DETAIL "Z"

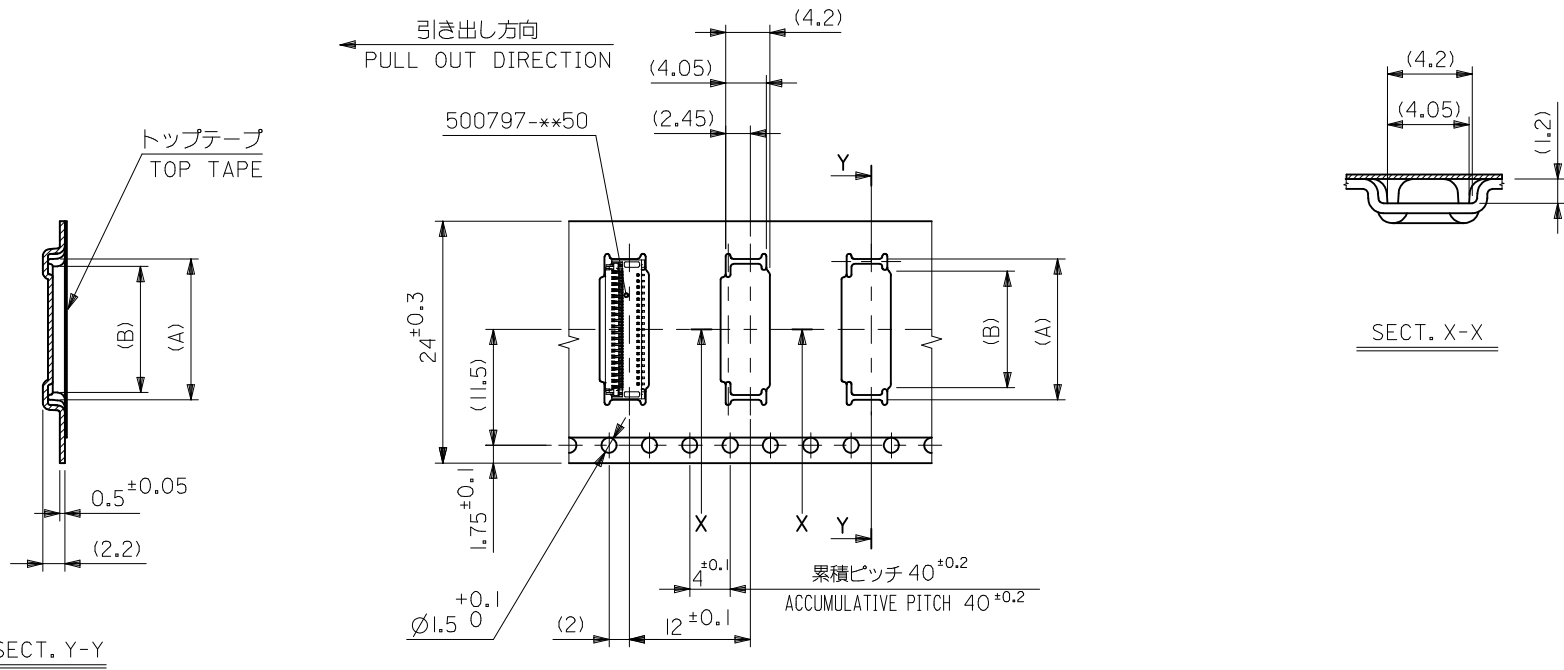
REVISED	EC NO: J2016-1099	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	500797-**94	MODEL NO.
	DRWN:MTAKAHASHI 04/2016/04/19	0.25 UNDER UNDER ±0.03		MM ONLY		---	METRIC	THIRD ANGLE PROJECTION	
	CHKD:KATAHASHI 2016/04/26	0.25 OVER 0.5 UNDER ±0.05		DRAWN BY DATE		TITLE			
	APPR:KUSUHARA01 2016/04/28	0.5 OVER 1.0 UNDER ±0.1		YMAEDA 2006/03/07		EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE-			
G	REV	1.0 OVER 10 UNDER ±0.2		CHECKED BY DATE		MATERIAL NO. DOCUMENT NO. SHEET NO.			
		10 OVER 30 UNDER ±0.25		MTANAKA 2006/03/07					
		30 OVER ±0.3		APPROVED BY DATE		SEE CHART SD-500797-006 1 OF 3			
		ANGULAR ±3 °		NUKITA 2006/03/07					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				A3					



16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	17.5	3.4	5.6	500797-1194	11
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 Ck+
				500797-**94	MODEL No.

REVISED EC NO: J2016-1099 DRWN:MTAKAHASHI 04/2016/04/19 CHKD:KATAHASHI 2016/04/26 APPR:KUSUHARA01 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY MTANAKA	DATE 2006/03/07		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE 2006/03/07		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.
10 OVER	30 UNDER	±0.25	SEE CHART		SD-500797-006	2 OF 3	
30 OVER		±0.3	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
ANGULAR		±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				



24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	25.5	10.0	12.2	500797-3394	33
		9.4	11.6	500797-3194	31
		8.2	10.4	500797-2794	27
		7.0	9.2	500797-2394	23
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 Ck+
		500797-**-94		MODEL No.	

REVISED EC NO: J2016-1099 DRWN:MTAKAHASHI 2016/04/19 CHKD:KTAHAKASHI 2016/04/26 APPR:TKUSUHARA01 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY MTANAKA	DATE 2006/03/07	molex	
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE 2006/03/07		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.	DOCUMENT NO.	SEE CHART	SD-500797-006
10 OVER	30 UNDER	±0.25	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER		±0.3	SIZE A3				